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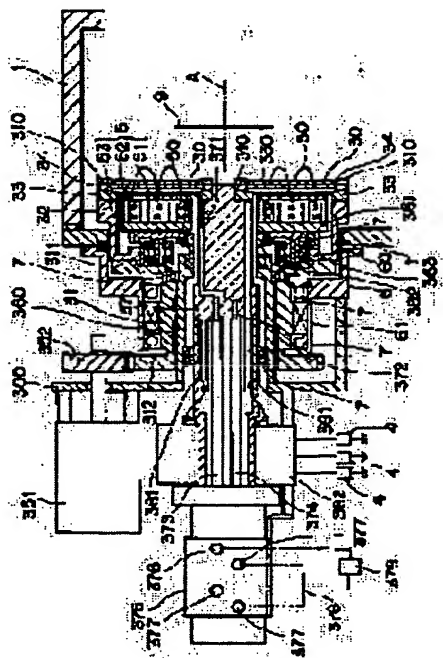
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(54) SPUTTERING SYSTEM

(57)Abstract:

PROBLEM TO BE SOLVED: To deposit a uniform thin film without rotating a base board in a sputtering system.

SOLUTION: A target 30 is sputtered by means of sputtering electric discharge to deposit the thin film of a material of the target 30 on the surface of the base board 9. A plurality of the targets 30 are provided on the circumference of a circle coaxial with the center axis A of the base board 9 and turn round the rotation axis coaxial with the center axis of the base board 9 by means of a main rotation mechanism. In the power supply system for introducing electric power for sputtering electric discharge to the respective targets 30, the electric power to be supplied can be independently controlled. By the main rotation mechanism, a magnet mechanism 5 for forming sputtering electric discharge into magnetron discharge can be rotated integrally with the targets 30. The magnet mechanism 5 forms a magnetic field asymmetrical about the center axis of the targets 30 and rotates on the center axis of the targets 30 by means of a sub-rotation mechanism. The sub-rotation mechanism rotates the magnet mechanism 5 by the rotational power of the main rotation mechanism.



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